**CT100** March 2019



# **CT100**

#### 1D Linear Sensor

#### **Features**

• Operating Magnetic Field Range: ±20 mT

• Stable Magnetic Performance over Temperature

Linearity Error: ±0.5%Differential Outputs

Supply Voltage: 1.0 V to 5.5 V

• Operating Temperature: -40°C to +150°C

Package Options:

o 6-lead SOT23

o 6-lead DFN,  $1.50 \times 1.50 \times 0.45$  mm

o KGD (Known Good Die) in Wafer Form

#### **Applications**

Linear Measurements

Proximity Sensing

Current Sensing

#### **Product Description**

The CT100 is a 1D linear sensor in full-bridge configuration from Crocus Technology developed on its patented MLU™ technology. The magnetic field range for the CT100 is from -20 mT to +20 mT and achieves a linearity error of ±0.5% while providing unparalleled temperature stability. It supports a wide operating voltage range of 1.0 V to 5.5 V.

It is available in a 6-lead SOT23 package and for space critical applications, a low profile and small form factor 6-lead DFN package that is  $1.50 \times 1.50 \times 0.45$  mm in size. The CT100 is also made available in die form where it will be shipped as unsawn wafers (wafer map files will be provided to indicate known good die).

### Ordering Information

Part Number	Operating Temperature Range	Output Type	Package	Packing Method	
CT100LW-IS6	-40°C to +85°C		0.11.00700		
CT100LW-HS6	-40°C to +125°C	Differential	6-lead SOT23 2.90 x 2.80 x 1.20 mm	Tape & Reel	
CT100LW-FS6	-40°C to +150°C		2.90 X 2.00 X 1.20 Hilli		
CT100LW-ID6	-40°C to +85°C		C Is a d DEN		
CT100LW-HD6	-40°C to +125°C	Differential	6-lead DFN 1.50 x 1.50 x 0.45 mm	Tape & Reel	
CT100LW-FD6	-40°C to +150°C		1.50 X 1.50 X 0.45 IIIII		
CT100LW-KGD	-40°C to +150°C	Differential	Wafer Form	Unsawn Wafer	

### **Block Diagram**

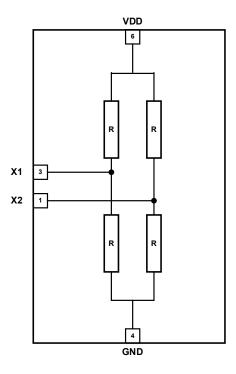


Figure 1. CT100 Functional Block Diagram for SOT23-6

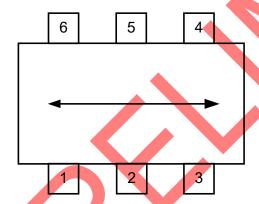


Figure 3. CT100 Axis of Sensitivity for SOT23-6 (Top Down View)

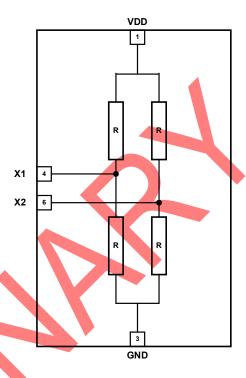


Figure 2. CT100 Functional Block Diagram for DFN-6

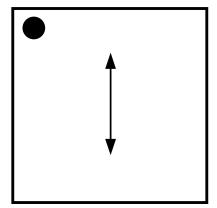


Figure 4. CT100 Axis of Sensitivity for DFN-6 (Top Down View)

## **Pin Configuration**

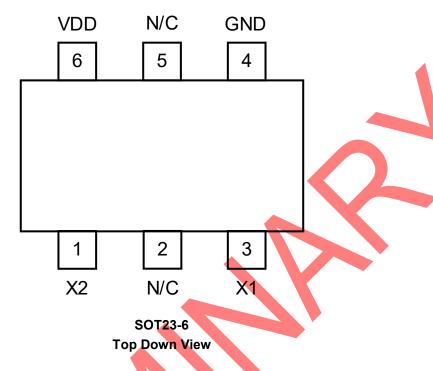
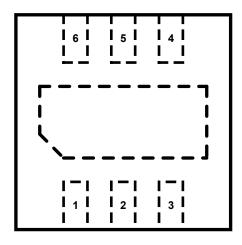


Figure 5. CT100 Pin-out Diagram

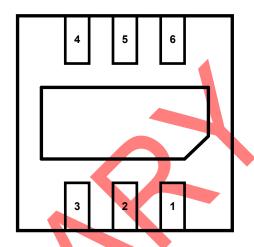
#### **Pin Definitions**

SOT23-6 Pin #	Pin Name	Pin Description
1	X2	Differential Output X2
2	N/C	No Connect
3	X1	Differential Output X1
4	GND	Ground
5	N/C	No Connect
6	VDD	Supply Voltage

## **Pin Configuration**



**DFN-6 – Top Down View** 



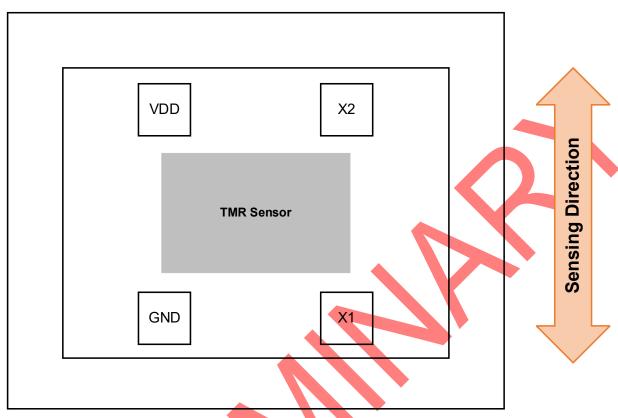
DFN-6 - Bottoms Up View

Figure 6. CT100 Pin-out Diagrams

#### **Pin Definitions**

DFN-6 Pin #	Pin Name	Pin Description
1	VDD	Supply Voltage
2	N/C	No Connect
3	GND	Ground
4	X1	Differential Output X1
5	N/C	No Connect
6	X2	Differential Output X2

## **Pad Configuration**



CT100 Die Layout and Axis of Sensitivity

Top Down View

Figure 7. CT100 Pad Diagram

## **Pad Definitions**

Pad #	Pad Name	Pad Description
1	VDD	Supply Voltage
2	X2	Differential Output X2
3	X1	Differential Output X1
4	GND	Ground

### **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the CT100 and may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter		Min.	Max.	Unit
$V_{DD}$	Supply Voltage		-0.3	6.0	V
V <sub>OUT</sub>	Analog Output Pins Maximum Voltage		-660	+660	mV
ESD	Electrostatic Discharge	Human Body Model (HBM) per JESD22-A114	±4.0		IAV.
ESD	Protection Level	Charged Device Model (CDM) per JESD22-C101	±1.0		kV
B <sub>MAX</sub>	Maximum Magnetic Field			±200	mT
T <sub>STG</sub>	Storage Temperature		-65	+160	°C
TL	Lead Soldering Temperature, 10	) Seconds		+260	°C

#### **Recommended Operating Conditions**

The Recommended Operating Conditions table defines the conditions for actual operation of the CT100. Recommended operating conditions are specified to ensure optimal performance to the specifications. Crocus Technology does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter		Min.	Тур.	Max.	Unit
$V_{DD}$	Supply Voltage Range		1.0	3.0	5.5	V
Vout	OUT Voltage Range		-605		+605	mV
BOPERATING	Operating Magnetic Field				±20	mT
		Industrial	-40	+25	+85	
TA	Operating Ambient Temperature	Extended Industrial	-40	+25	+125	°C
		Full Range	-40	+25	+150	

### **Thermal Properties**

Junction-to-ambient thermal resistance is a function of application and board layout and is determined in accordance to JEDEC standard JESD51-7 for a four (4) layer 2s2p FR-4 printed circuit board (PCB) with 2 oz. of copper (Cu). Special attention must be paid not to exceed junction temperature T<sub>J(MAX)</sub> at a given ambient temperature T<sub>A</sub>.

Symbol	Parameter	Min.	Тур.	Max.	Unit
$\theta$ JA_SOT23	Junction-to-Ambient Thermal Resistance, SOT23-6		202		°C/W
θJA_DFN6	Junction-to-Ambient Thermal Resistance, DFN-6		165		°C/W

### **Electrical & Magnetic Specifications**

Unless otherwise specified:  $V_{DD}$  = 1.0 V to 5.5 V and  $T_A$  = -40°C to +150°C. Typical values are  $V_{DD}$  = 3.0 V and  $T_A$  = +25°C.

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
Magnetic					1	
Boperating	Operating Magnetic Field (2)				±20	mT
Electrical				4		
RBRIDGE	Bridge Resistance		20		40	kΩ
D-	Power Consumption	$V_{DD} = 3.0 V,$		0.45		mW
P <sub>D</sub>	Power Consumption	$R_{BRIDGE} = 30 \text{ k}\Omega$		0.45		IIIVV
V <sub>OFFSET</sub>	Offset Voltage		-5		+5	mV/V
S	Sensitivity (Full-bridge Gain)	Boperating = ±20 mT	3.5	4.0	4.5	mV/V/mT
TCR <sub>BRDIGE</sub>	Temperature Coefficient Resistance of Bridge (1)				600	ppm/°C
TCO	Temperature Coefficient of Offset Voltage (1)		V		3.0	μV/V/°C
TCS	Temperature Coefficient of Sensitivity (1)				-300	ppm/°C
L	Linearity (1)	$B_{OP} = \pm 20 \text{ mT}$			±0.5	%
e <sub>N</sub>	Output Noise (1)	$f_{BW} = 0.1$ Hz to 1 kHz, $V_{DD} = 3.0$ V			10.0	μV <sub>RMS</sub>

<sup>(1)</sup> Guaranteed by design and characterization.

#### **Electrical Characteristics**

 $V_{DD} = 3.0 \text{ V}$  and  $T_A = +25^{\circ}\text{C}$ .

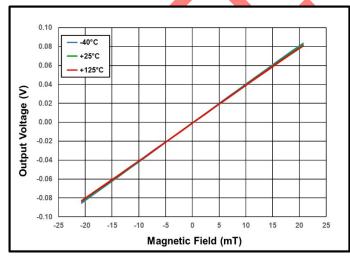


Figure 8. Sensitivity: Output Voltage vs. Magnetic Field vs. Temperature

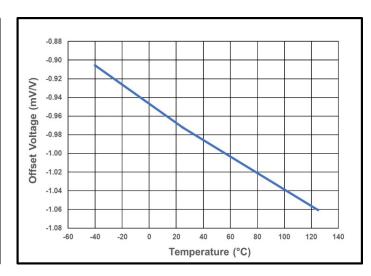


Figure 9. Offset Voltage vs. Temperature

<sup>(2)</sup> Wider operating magnetic field range available upon request.

## **Recommended Application Circuit**

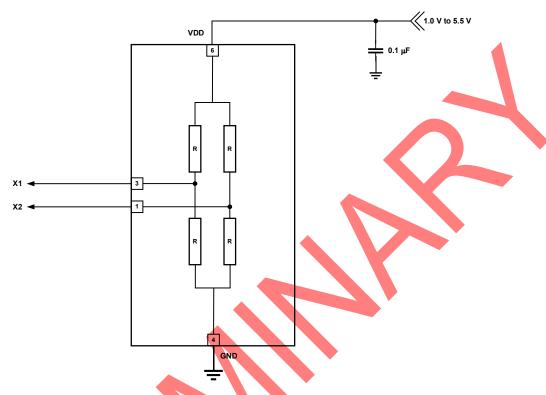


Figure 10. CT100 Application Diagram

Table 1. Recommended External Components

Component	Description	Vendor & Part Number	Parameter	Min.	Тур.	Max.	Unit
Свур	0.1 μ <b>F</b> , X7R	Murata GRM033Z71A104KE14 Others	С		0.1		μF

## **SOT23-6 Package Drawing and Dimensions**

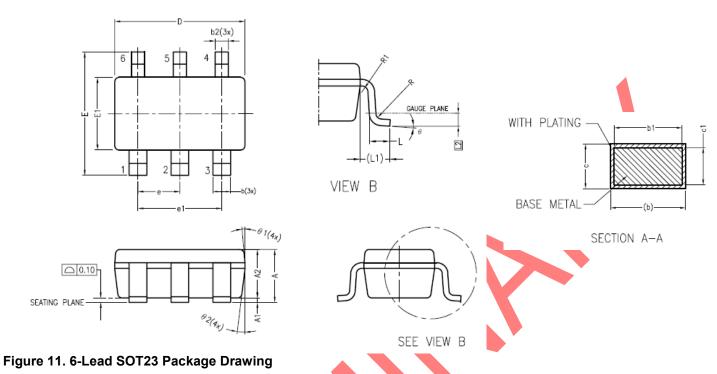
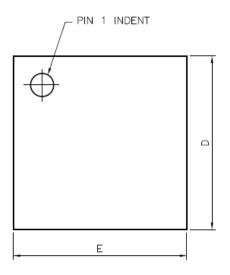


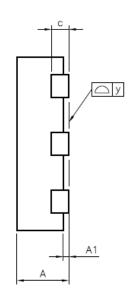
Table 2. CT100 6-Lead SOT23 Package Dimensions

	Dimensions in Millimeters (mm)						
Symbol							
Cymbol	Min.	Тур.	Max.				
Α	1.05	1.20	1.35				
A1	0.00	0.10	0.15				
A2	1.00	1.10	1.20				
b	0.40	-	0.50				
b1	0.40	0.40	0.45				
С	0.08	-	0.22				
c1	0.08	0.13	0.20				
D	2.80	2.90	3.00				
E	2.60	2.80	3.00				
E1	1.50	1.60	1.70				
е		0.95 BSC					
e1		1.90 BSC					
L	0.35	0.43	0.60				
L1		0.60 REF					
L2		0.25 BSC					
R	0.10	-	-				
R1	0.10	-	0.25				
θ	0°	4°	8°				
θ1	5°	6°	15°				
θ2	5°	8°	15°				

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### **DFN-6 Package Drawing and Dimensions**





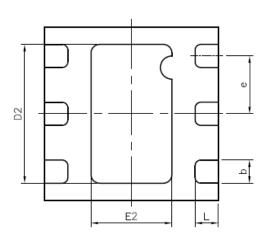


Figure 12. DFN-6 Package Drawing

Table 3. CT100 DFN-6 Package Dimensions

Symbol	Dimensions in Millimeters (mm)					
Symbol	Min.	Тур.	Max.			
Α	0.40	0.45	0.50			
A1	0.00	0.02	0.05			
b	0.15	0.20	0.25			
С		0.15 REF	-			
D	1.40	1.50	1.60			
D2	1.15	1.20	1.25			
Ē	1.40	1.50	1.60			
E2	0.65	0.70	0.75			
е	-	0.50	-			
L	0.15	0.20	0.25			
у	0.000	-	0.075			

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### **Package Information**

**Table 4. CT100 Package Information** 

Part Number	Package Type	# of Leads	Package Quantity	Lead Finish	Eco Plan (1)	MSL Rating (2)	Operating Temperature <sup>(3)</sup>	Device Marking
CT100LW-IS6	SOT23	6	3,000	Sn	Green & RoHS	1	-40°C to +85°C	CT YWWS
CT100LW-HS6	SOT23	6	3,000	Sn	Green & RoHS	1	-40°C to +125°C	CT YWWS
CT100LW-FS6	SOT23	6	3,000	Sn	Green & RoHS	1	-40°C to +150°C	CT YWWS
CT100LW-ID6	DFN	6	3,000	Sn	Green & RoHS	1	-40°C to +85°C	C YZ
CT100LW-HD6	DFN	6	3,000	Sn	Green & RoHS	1	-40°C to +125°C	C YZ
CT100LW-FD6	DFN	6	3,000	Sn	Green & RoHS	1	-40°C to +150°C	C YZ

- (1) RoHS is defined as semiconductor products that are compliant to the current EU RoHS requirements. It also will meet the requirement that RoHS substances do not exceed 0.1% by weight in homogeneous materials. Green is defined as the content of Chlorine (CI), Bromine (Br) and Antimony Trioxide based flame retardants satisfy JS709B low halogen requirements of ≤ 1,000 ppm.
- (2) MSL Rating = Moisture Sensitivity Level Rating as defined by JEDEC standard classifications.
- (3) Package will withstand ambient temperature range of -40°C to +150°C and storage temperature range of -65°C to +160°C.
- (4) Device Marking for SOT23 is defined as XZ YWWS where XZ = part number, Y = year, WW = work week and S = sequential number. DFN is defined as X where X = part number and YZ = date code information.





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<b>Data Sheet Identification</b>	Product Status	Definition
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